

Title (en)

ATTACHMENT OF SEMICONDUCTOR DIE TO LEAD FRAME BY MEANS OF AN ADHESIVE RESIN.

Title (de)

VERBINDUNG ZWISCHEN EINEM HALBLEITERPLÄTTCHEN UND EINEM LEITERRAHMEN MITTELS EINES KLEBEHARZES.

Title (fr)

FIXATION D'UN DE DE SEMICONDUCTEUR A UN CADRE DE MONTAGE A CONDUCTEURS AU MOYEN D'UNE RESINE ADHESIVE.

Publication

**EP 0333734 A1 19890927 (EN)**

Application

**EP 87907718 A 19871112**

Priority

US 93060086 A 19861113

Abstract (en)

[origin: WO8803704A1] Semiconductor packages are fabricated by first depositing an adhesive resin (6) composition on the paddle (8) of a lead frame (2), activating the adhesive resin by rapidly raising its temperature and then depositing a die (16) on the activated adhesive. Conventional wire bonding and encapsulating steps follow to afford the semiconductor package.

Abstract (fr)

On fabrique des modules à semiconducteurs en déposant d'abord une composition de résine adhésive (6) sur la plaquette (8) d'un cadre de montage à connecteurs (2), en activant la résine adhésive par élévation rapide de sa température, puis en déposant un dé (16) sur la résine adhésive activée. On passe ensuite aux étapes traditionnelles de soudage des fils conducteurs et d'encapsulation pour obtenir le module à semiconducteurs.

IPC 1-7

**H01L 21/58**

IPC 8 full level

**C09J 5/06** (2006.01); **C09J 179/08** (2006.01); **H01L 21/52** (2006.01); **H01L 21/58** (2006.01); **H01L 21/60** (2006.01); **H01L 23/482** (2006.01)

CPC (source: EP KR)

**H01L 21/50** (2013.01 - KR); **H01L 23/4828** (2013.01 - EP); **H01L 24/29** (2013.01 - EP); **H01L 24/75** (2013.01 - EP); **H01L 24/83** (2013.01 - EP); **H01L 24/45** (2013.01 - EP); **H01L 2224/2919** (2013.01 - EP); **H01L 2224/2929** (2013.01 - EP); **H01L 2224/29339** (2013.01 - EP); **H01L 2224/29344** (2013.01 - EP); **H01L 2224/29364** (2013.01 - EP); **H01L 2224/29369** (2013.01 - EP); **H01L 2224/29376** (2013.01 - EP); **H01L 2224/29378** (2013.01 - EP); **H01L 2224/29386** (2013.01 - EP); **H01L 2224/45124** (2013.01 - EP); **H01L 2224/45144** (2013.01 - EP); **H01L 2224/75265** (2013.01 - EP); **H01L 2224/8319** (2013.01 - EP); **H01L 2224/83224** (2013.01 - EP); **H01L 2224/8385** (2013.01 - EP); **H01L 2924/00013** (2013.01 - EP); **H01L 2924/00014** (2013.01 - EP); **H01L 2924/01005** (2013.01 - EP); **H01L 2924/01006** (2013.01 - EP); **H01L 2924/01012** (2013.01 - EP); **H01L 2924/01013** (2013.01 - EP); **H01L 2924/01014** (2013.01 - EP); **H01L 2924/0103** (2013.01 - EP); **H01L 2924/01033** (2013.01 - EP); **H01L 2924/01044** (2013.01 - EP); **H01L 2924/01046** (2013.01 - EP); **H01L 2924/01047** (2013.01 - EP); **H01L 2924/01051** (2013.01 - EP); **H01L 2924/01076** (2013.01 - EP); **H01L 2924/01077** (2013.01 - EP); **H01L 2924/01078** (2013.01 - EP); **H01L 2924/01079** (2013.01 - EP); **H01L 2924/01082** (2013.01 - EP); **H01L 2924/0665** (2013.01 - EP); **H01L 2924/07802** (2013.01 - EP); **H01L 2924/0781** (2013.01 - EP); **H01L 2924/09701** (2013.01 - EP); **H01L 2924/15787** (2013.01 - EP); **H01L 2924/3025** (2013.01 - EP)

Citation (search report)

See references of WO 8803704A1

Cited by

CN111500212A

Designated contracting state (EPC)

CH DE FR GB IT LI NL SE

DOCDB simple family (publication)

**WO 8803704 A1 19880519**; BR 8707876 A 19900301; CN 87107692 A 19880525; EP 0333734 A1 19890927; JP H01502868 A 19890928; KR 890700267 A 19890310; KR 910006966 B1 19910914

DOCDB simple family (application)

**US 8702952 W 19871112**; BR 8707876 A 19871112; CN 87107692 A 19871106; EP 87907718 A 19871112; JP 50715487 A 19871112; KR 880700809 A 19880712